

LMC606x Precision CMOS, Micropower Operational Amplifiers

1 Features

- Typical values unless otherwise noted
- Low offset voltage: $100\mu\text{V}$
- Ultra-low supply current: $16\mu\text{A}/\text{amplifier}$
- Supply range: 4.5V to 15V
- Ultra-low input bias current: 10fA
- Output swing within 10mV of supply rail, $100\text{k}\Omega$ load
- Input common-mode includes V_-
- High voltage gain: 140dB
- Improved latchup immunity

2 Applications

- Instrumentation amplifier
- Photodiode and infrared detector preamplifier
- Transducer amplifiers
- Portable analytic instruments
- Medical instrumentation
- Digital-to-analog converter (DAC)
- Charge amplifier for piezoelectric transducers

3 Description

The LMC6061, LMC6062, and LMC6064 (LMC606x) are precision, low-offset-voltage, micropower operational amplifiers (op amps), capable of precision single-supply operation. Performance characteristics include ultra-low input bias current, high voltage gain, rail-to-rail output swing, and an input common-mode voltage range that includes ground. These features, plus the low power consumption of the op amps, make the LMC606x an excellent choice for battery-powered applications.

Other applications using the LMC606x include precision full-wave rectifiers, integrators, references, sample-and-hold circuits, and true instrumentation amplifiers.

This device is built with TI's advanced double-poly silicon-gate CMOS process.

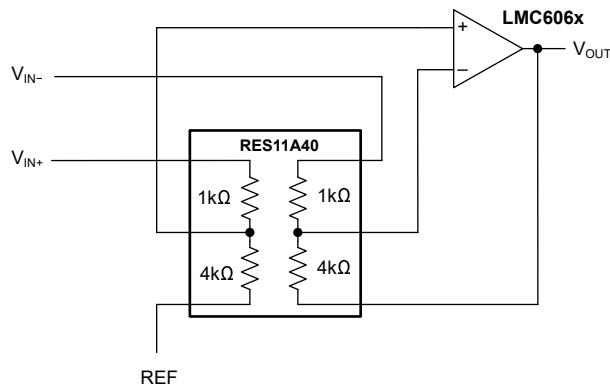
For designs that require higher speed, see the [LMC608x](#) precision operational amplifiers.

PATENT PENDING

Device Information

PART NUMBER	CHANNEL COUNT	PACKAGE ⁽¹⁾
LMC6061	Single	D (SOIC, 8)
LMC6062	Dual	D (SOIC, 8) P (PDIP, 8)
LMC6064	Quad	D (SOIC, 8)

(1) For more information, see [Section 9](#).



Difference Amplifier Application With RES11A



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Table of Contents

1 Features.....	1	6 Application and Implementation.....	15
2 Applications.....	1	6.1 Applications Information.....	15
3 Description.....	1	6.2 Typical Applications.....	17
4 Pin Configuration and Functions.....	2	6.3 Layout.....	18
5 Specifications.....	5	7 Device and Documentation Support.....	20
5.1 Absolute Maximum Ratings.....	5	7.1 Receiving Notification of Documentation Updates....	20
5.2 ESD Ratings.....	5	7.2 Support Resources.....	20
5.3 Recommended Operating Conditions.....	5	7.3 Trademarks.....	20
5.4 Thermal Information: LMC6061.....	6	7.4 Electrostatic Discharge Caution.....	20
5.5 Thermal Information: LMC6062.....	6	7.5 Glossary.....	20
5.6 Thermal Information: LMC6064.....	6	8 Revision History.....	20
5.7 Electrical Characteristics.....	7	9 Mechanical, Packaging, and Orderable Information.....	21
5.8 Typical Characteristics.....	11		

4 Pin Configuration and Functions

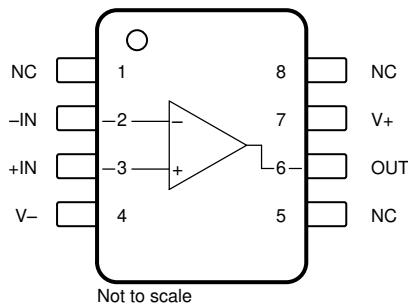


Figure 4-1. LMC6061: D Package, 8-Pin SOIC (Top View)

Table 4-1. Pin Functions: LMC6061

PIN		TYPE	DESCRIPTION
NAME	NO.		
-IN	2	Input	Inverting input
+IN	3	Input	Noninverting input
NC	1, 8, 5	—	No connection (can be left floating)
OUT	6	Output	Output
V-	4	Power	Negative (lowest) power supply
V+	7	Power	Positive (highest) power supply

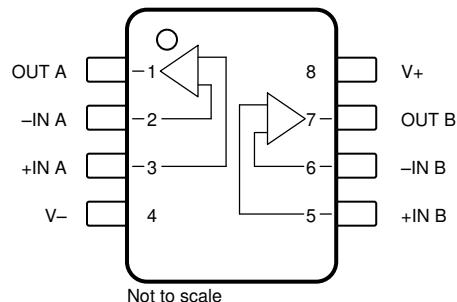


Figure 4-2. LMC6062: D Package, 8-Pin SOIC and P Package, 8-Pin PDIP (Top View)

Table 4-2. Pin Functions: LMC6062

PIN		TYPE	DESCRIPTION
NAME	NO.		
-IN A	2	Input	Inverting input channel A
-IN B	6	Input	Inverting input channel B
+IN A	3	Input	Noninverting input channel A
+IN B	5	Input	Noninverting input channel B
OUT A	1	Output	Output channel A
OUT B	7	Output	Output channel B
V-	4	Power	Negative supply
V+	8	Power	Positive supply

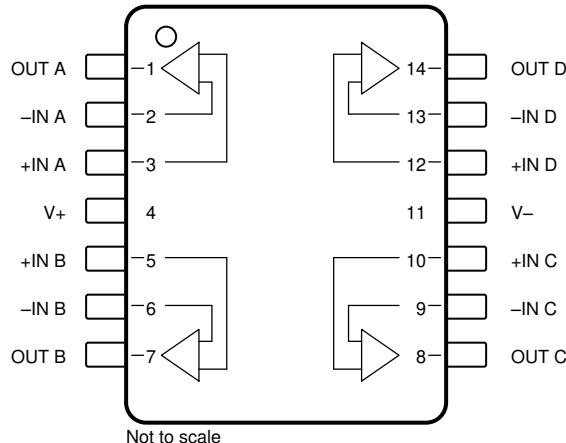


Figure 4-3. LMC6064: D Package, 14-Pin SOIC (Top View)

Table 4-3. Pin Functions: LMC6064

PIN		TYPE	DESCRIPTION
NAME	NO.		
-IN A	2	Input	Inverting input channel A
-IN B	6	Input	Inverting input channel B
-IN C	9	Input	Inverting input channel C
-IN D	13	Input	Inverting input channel D
+IN A	3	Input	Noninverting input channel A
+IN B	5	Input	Noninverting input channel B
+IN C	10	Input	Noninverting input channel C
+IN D	12	Input	Noninverting input channel D
OUT A	1	Output	Output channel A
OUT B	7	Output	Output channel B
OUT C	8	Output	Output channel C
OUT D	14	Output	Output channel D
V-	11	Power	Negative supply
V+	4	Power	Positive supply

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)^{(1) (2)}

		MIN	MAX	UNIT
	Differential input voltage		±Supply voltage	V
	Voltage at input/output pin	(V ₋) – 0.3	(V ₊) + 0.3	V
V _S	Supply voltage, V _S = (V ₊) – (V ₋)		16	V
I _{SC}	Output short circuit current	To V ₊	See ⁽³⁾	
		To V ₋	See ⁽⁴⁾	
Current		At input pin	±10	
		At output pin	±30	mA
		At power supply pin	40	
	Power dissipation		See ⁽⁵⁾	
	Lead temperature (soldering, 10s)		260	°C
T _J	Junction temperature		150	°C
T _{stg}	Storage temperature	–65	150	°C

- (1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
- (3) Do not connect output to V₊, when V₊ is greater than 13V or reliability can be adversely affected.
- (4) Applies to both single-supply and split-supply operation. Continuous short circuit operation at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150°C. Output currents in excess of ±30mA over long term can adversely affect reliability.
- (5) The maximum power dissipation is a function of T_{J(Max)}, θ_{JA}, and T_A. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(Max)} – T_A) / θ_{JA}

5.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT	
V _S	Supply voltage, V _S = (V ₊) – (V ₋)	Single supply	4.5	36	V	
		Dual supply	±2.25	±18		
Specified temperature		–40	125		°C	
Power dissipation			See ⁽¹⁾			

- (1) To operate the device at elevated temperatures, derate the device based on thermal resistance θ_{JA} with P_D = (T_J – T_A) / θ_{JA}.

5.4 Thermal Information: LMC6061

THERMAL METRIC ⁽¹⁾		LMC6061	UNIT
		D (SOIC)	
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	193.0	°C/W
$R_{\theta JC(\text{top})}$	Junction-to-case(top) thermal resistance	57.9	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	62.3	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	10.0	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	61.5	°C/W
$R_{\theta JC(\text{bot})}$	Junction-to-case(bottom) thermal resistance	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

5.5 Thermal Information: LMC6062

THERMAL METRIC ⁽¹⁾		LMC6062		UNIT
		D (SOIC)	P (PDIP)	
		8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	193.0	115.0	°C/W
$R_{\theta JC(\text{top})}$	Junction-to-case(top) thermal resistance	52.0	59.2	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	56.9	43.2	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	6.8	25.1	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	56.1	42.3	°C/W
$R_{\theta JC(\text{bot})}$	Junction-to-case(bottom) thermal resistance	N/A	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

5.6 Thermal Information: LMC6064

THERMAL METRIC ⁽¹⁾		LMC6064	UNIT
		D (SOIC)	
		14 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	126.0	°C/W
$R_{\theta JC(\text{top})}$	Junction-to-case(top) thermal resistance	34.6	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	34.3	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	4.7	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	33.7	°C/W
$R_{\theta JC(\text{bot})}$	Junction-to-case(bottom) thermal resistance	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

5.7 Electrical Characteristics

at $T_J = T_A = +25^\circ\text{C}$, $V+ = 5\text{V}$, $V- = 0\text{V}$, $V_{\text{CM}} = 1.5\text{V}$, $V_{\text{OUT}} = 2.5\text{V}$, and $R_L > 1\text{M}\Omega$ connected to $V+ / 2$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFFSET VOLTAGE						
V_{OS}	Input offset voltage	LMC606xAI	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	± 100	± 350	μV
		LMC606xI	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	± 100	± 800	
dV_{OS}/dT	Input offset voltage drift	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		1		$\mu\text{V}/^\circ\text{C}$
PSRR	Power supply rejection ratio	Positive $5\text{V} \leq V+ \leq 15\text{V}$, $V_{\text{OUT}} = 2.5\text{V}$,	LMC606xAI	75	85	dB
			LMC606xAI $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	72		
			LMC606xI	66	85	
			LMC606xI $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	63		
			LMC606xAI	84	100	
		Negative $-10\text{V} \leq V+ \leq 0\text{V}$	LMC606xAI $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	81		
			LMC606xI	74	100	
			LMC606xI $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	71		
INPUT BIAS CURRENT						
I_B	Input bias current			± 10		fA
		$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$			± 4	pA
I_{OS}	Input offset current			± 5		fA
		$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$			± 4	pA
NOISE						
e_n	Input voltage noise density	$f = 1\text{kHz}$		83		$\text{nV}/\sqrt{\text{Hz}}$
i_n	Input current noise density	$f = 1\text{kHz}$		12.5		$\text{fA}/\sqrt{\text{Hz}}$
THD	Total Harmonic Distortion	$f = 1\text{kHz}$, $G = -5\text{V/V}$, $R_L = 100\text{k}\Omega$, $V_{\text{OUT}} = 2\text{V}_{\text{pp}}$, $V_S = \pm 5\text{V}$		0.01		%
INPUT VOLTAGE						
V_{CM}	Common-mode voltage	To positive rail $V+ = 15\text{V}$ and $V- = 5\text{V}$, CMRR > 60dB	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	$(V+) - 1.9$	$(V+) - 2.3$	V
					$(V+) - 2.5$	
		To negative rail $V+ = 15\text{V}$ and $V- = 5\text{V}$, CMRR > 60dB	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	- 0.1	- 0.4	
				0		
CMRR	Common-mode rejection ratio	$V+ = 15\text{V}$, $0\text{V} \leq V_{\text{CM}} \leq 12\text{V}$	LMC606xAI	75	85	dB
			LMC606xAI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	72		
			LMC606xI	66	85	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	63		
INPUT IMPEDANCE						
R_{IN}	Input resistance			>10		$\text{T}\Omega$

5.7 Electrical Characteristics (continued)

at $T_J = T_A = +25^\circ\text{C}$, $V+ = 5\text{V}$, $V- = 0\text{V}$, $V_{CM} = 1.5\text{V}$, $V_{OUT} = 2.5\text{V}$, and $R_L > 1\text{M}\Omega$ connected to $V+ / 2$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
OPEN-LOOP GAIN						
A_{OL}	Open-loop voltage gain	Sourcing, $V+ = 15\text{V}$, $V_{CM} = 7.5\text{V}$, $7.5\text{V} \leq V_O \leq 11.5\text{V}$, $R_L = 100\text{k}\Omega$	LMC606xAl	300	4000	V/mV
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	200		
			LMC606xI	300	4000	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	200		
		Sinking, $V+ = 15\text{V}$, $V_{CM} = 7.5\text{V}$, $2.5\text{V} \leq V_O \leq 7.5\text{V}$, $R_L = 100\text{k}\Omega$	LMC606xAl	180	3000	
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	100		
			LMC606xI	90	3000	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	60		
		Sourcing, $V+ = 15\text{V}$, $V_{CM} = 7.5\text{V}$, $7.5\text{V} \leq V_O \leq 11.5\text{V}$, $R_L = 25\text{k}\Omega$	LMC606xAl	300	3000	
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	150		
			LMC606xI	200	3000	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	80		
		Sinking, $V_S = 15\text{V}$, $V_{CM} = 7.5\text{V}$, $2.5\text{V} \leq V_O \leq 7.5\text{V}$, $R_L = 25\text{k}\Omega$	LMC606xAl	100	2000	
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	50		
			LMC606xI	70	2000	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	35		
FREQUENCY RESPONSE						
GBW	Gain bandwidth product				100	kHz
SR	Slew rate	$V+ = 15\text{V}$, 10V step, $g = 1$	LMC606xAl	20	35	V/ms
			LMC606xAl, -40°C to $+85^\circ\text{C}$	10		
			LMC606xI	15	35	
			LMC606xI, -40°C to $+85^\circ\text{C}$	7		
	Crosstalk	Dual and quad channel, $V+ = 15\text{V}$, $R_L = 100\text{k}\Omega$, $f = 100\text{Hz}$, $V_{OUT} = 12V_{pp}$			155	dB

5.7 Electrical Characteristics (continued)

at $T_J = T_A = +25^\circ\text{C}$, $V+ = 5\text{V}$, $V- = 0\text{V}$, $V_{CM} = 1.5\text{V}$, $V_{OUT} = 2.5\text{V}$, and $R_L > 1\text{M}\Omega$ connected to $V+ / 2$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
OUTPUT						
V_O	Voltage output swing	Positive rail $V+ = 5\text{V}$, $R_L = 100\text{k}\Omega$	LMC606xAl	4.990	4.995	V
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	4.980		
			LMC606xI	4.950	4.995	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	4.925		
		Negative rail $V+ = 5\text{V}$, $R_L = 100\text{k}\Omega$	LMC606xAl	0.005	0.010	
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	0.020		
			LMC606xI	0.005	0.050	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	0.075		
		Positive rail $V+ = 5\text{V}$, $R_L = 25\text{k}\Omega$	LMC606xAl	4.975	4.990	
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	4.965		
			LMC606xI	4.950	4.990	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	4.850		
		Negative rail $V+ = 5\text{V}$, $R_L = 25\text{k}\Omega$	LMC606xAl	0.010	0.020	
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	0.035		
			LMC606xI	0.010	0.050	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	0.150		
		Positive rail $V+ = 15\text{V}$, $R_L = 100\text{k}\Omega$	LMC606xAl	14.975	14.990	
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	14.965		
			LMC606xI	14.950	14.990	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	14.925		
		Negative rail $V+ = 15\text{V}$, $R_L = 100\text{k}\Omega$	LMC606xAl	0.010	0.025	
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	0.035		
			LMC606xI	0.010	0.050	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	0.075		
		Positive rail $V+ = 15\text{V}$, $R_L = 25\text{k}\Omega$	LMC606xAl	14.90	14.965	
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	14.850		
			LMC606xI	14.850	14.965	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	14.800		
		Negative rail $V+ = 15\text{V}$, $R_L = 25\text{k}\Omega$	LMC606xAl	0.025	0.050	
			LMC606xAl, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	0.150		
			LMC606xI	0.025	0.100	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	0.200		

5.7 Electrical Characteristics (continued)

at $T_J = T_A = +25^\circ\text{C}$, $V+ = 5\text{V}$, $V- = 0\text{V}$, $V_{CM} = 1.5\text{V}$, $V_{OUT} = 2.5\text{V}$, and $R_L > 1\text{M}\Omega$ connected to $V+ / 2$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{SC}	Short-circuit current	Sourcing $V_{OUT} = 0\text{V}$	LMC606xAI	16	22	mA
			LMC606xAI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	10		
			LMC606xI	13	22	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	8		
		Sinking $V_{OUT} = 5\text{V}$	LMC606xAI	16	21	
			LMC606xAI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	8		
			LMC606xI	16	21	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	8		
		Sourcing $V+ = 15\text{V}$, $V_{OUT} = 0\text{V}$	LMC606xAI	15	25	
			LMC606xAI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	10		
			LMC606xI	15	25	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	10		
		Sinking $V+ = 15\text{V}$, $V_{OUT} = 13\text{V}^{(1)}$	LMC606xAI	20	26	
			LMC606xAI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	8		
			LMC606xI	20	26	
			LMC606xI, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	8		
POWER SUPPLY						
I_Q	Quiescent current per amplifier	LMC6061AI, $V_{OUT} = 1.5\text{V}$		20	24	μA
			$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		32	
		LMC6061I, $V_{OUT} = 1.5\text{V}$		20	32	
			$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		40	
		LMC6062AI and LMC6064AI, $V_{OUT} = 1.5\text{V}$		16	19	
			$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		23	
		LMC6062I and LMC6064I, $V_{OUT} = 1.5\text{V}$		16	23	
			$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		28	
		LMC6061AI, $V_{OUT} = 7.5\text{V}$, $V+ = 15\text{V}$		24	30	
			$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		38	
		LMC6061I, $V_{OUT} = 7.5\text{V}$, $V+ = 15\text{V}$		24	40	
			$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		48	
		LMC6062AI and LMC6064AI, $V_{OUT} = 7.5\text{V}$, $V+ = 15\text{V}$		20	23.5	
			$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		27.5	
		LMC6062I and LMC6064I, $V_{OUT} = 7.5\text{V}$, $V+ = 15\text{V}$		20	28.5	
			$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		33	

(1) Do not connect output to $V+$, when $V+$ is greater than 13V or reliability can be adversely affected.

5.8 Typical Characteristics

at $V_S = \pm 7.5V$ and $T_A = 25^\circ C$ (unless otherwise specified)

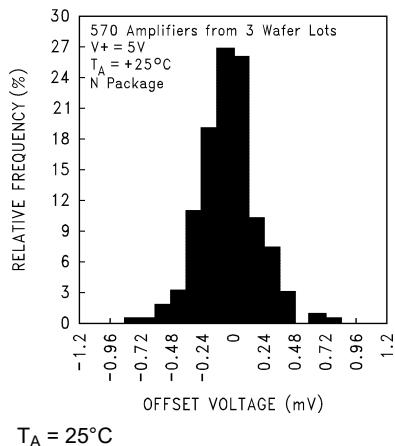


Figure 5-1. Distribution of Input Offset Voltage

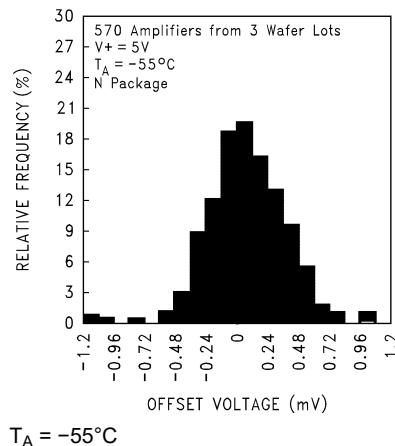


Figure 5-2. Distribution of Input Offset Voltage

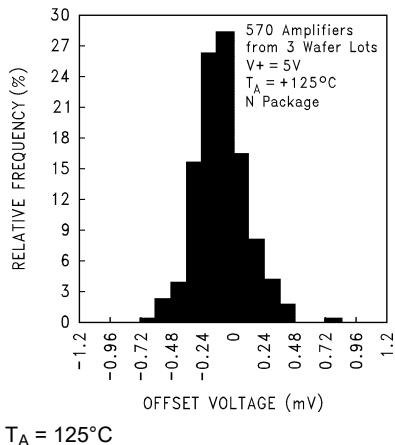


Figure 5-3. Distribution of Input Offset Voltage

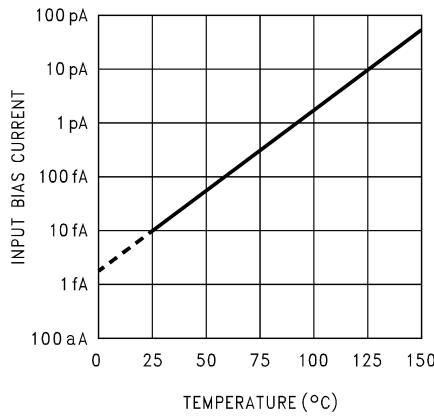


Figure 5-4. Input Bias Current vs Temperature

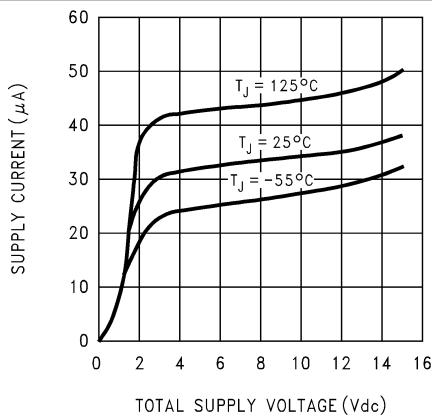


Figure 5-5. Supply Current vs Supply Voltage

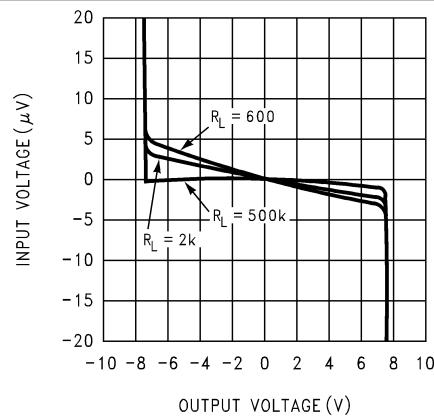


Figure 5-6. Input Voltage vs Output Voltage

5.8 Typical Characteristics (continued)

at $V_S = \pm 7.5V$ and $T_A = 25^\circ C$ (unless otherwise specified)

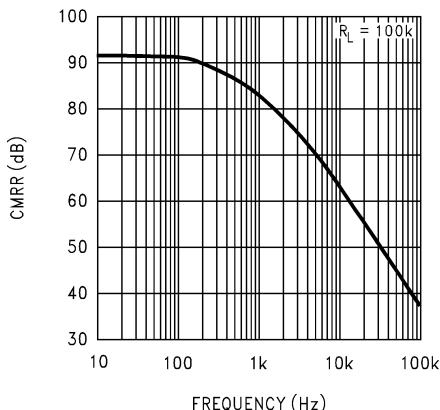


Figure 5-7. Common Mode Rejection Ratio vs Frequency

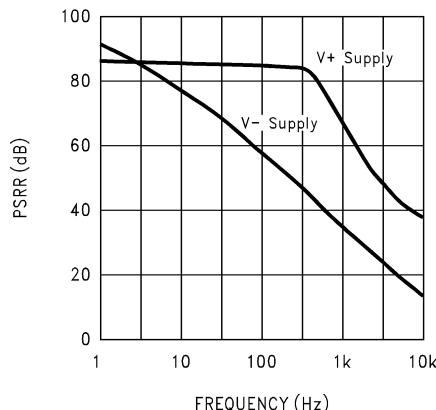


Figure 5-8. Power Supply Rejection Ratio vs Frequency

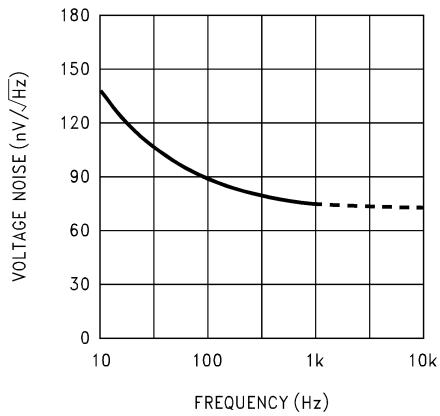


Figure 5-9. Input Voltage Noise vs Frequency

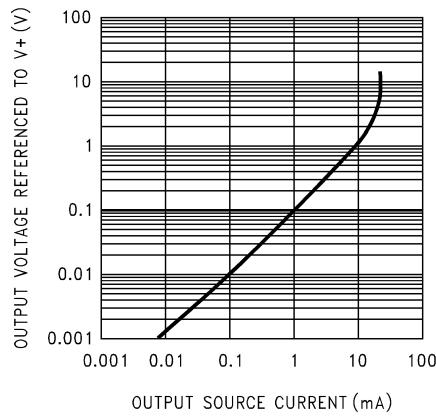


Figure 5-10. Output Characteristics Sourcing Current

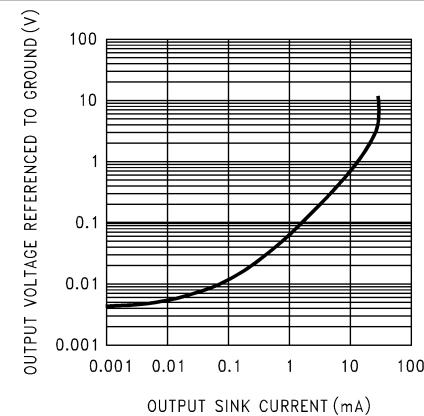


Figure 5-11. Output Characteristics Sinking Current

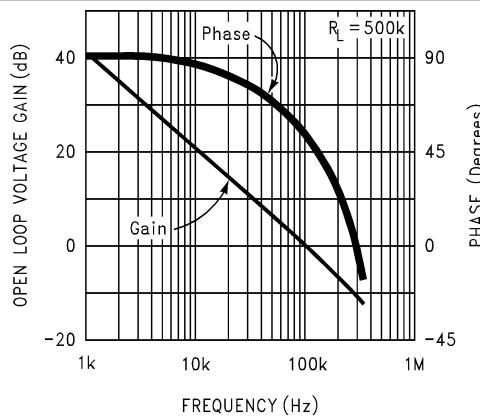


Figure 5-12. Gain and Phase Response vs Temperature

5.8 Typical Characteristics (continued)

at $V_S = \pm 7.5V$ and $T_A = 25^\circ C$ (unless otherwise specified)

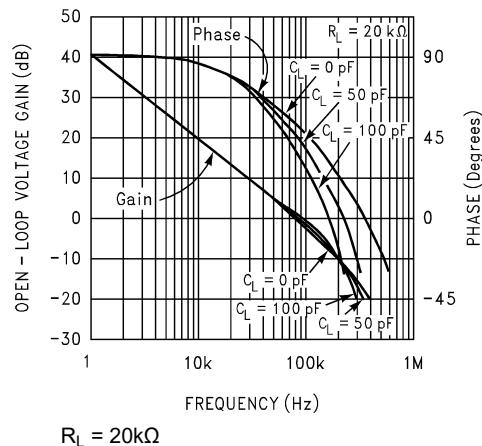


Figure 5-13. Gain and Phase Response vs Capacitive Load

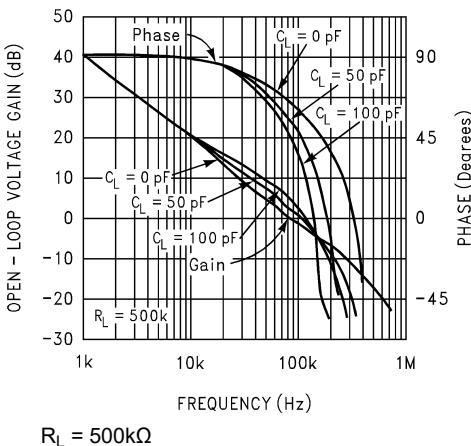


Figure 5-14. Gain and Phase Response vs Capacitive Load

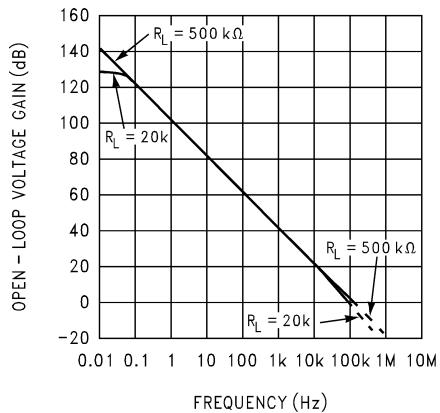


Figure 5-15. Open-Loop Frequency Response

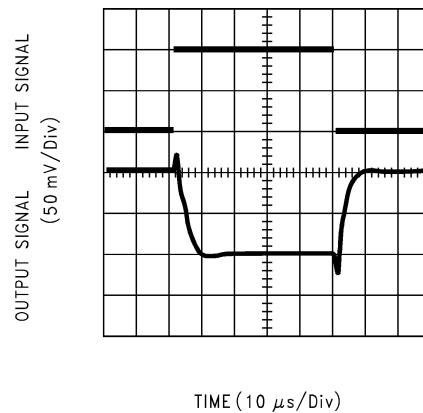


Figure 5-16. Inverting Small-Signal Pulse Response

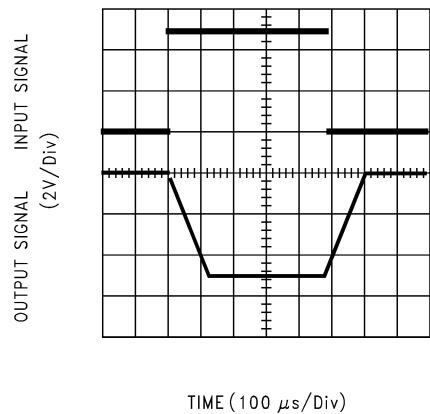


Figure 5-17. Inverting Large-Signal Pulse Response

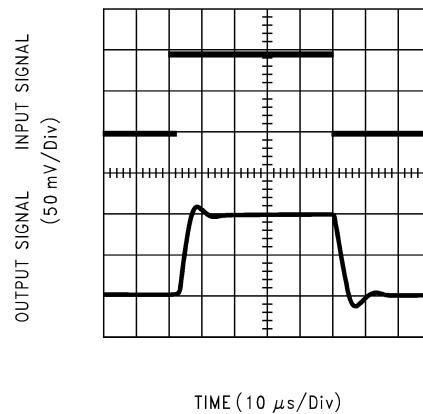
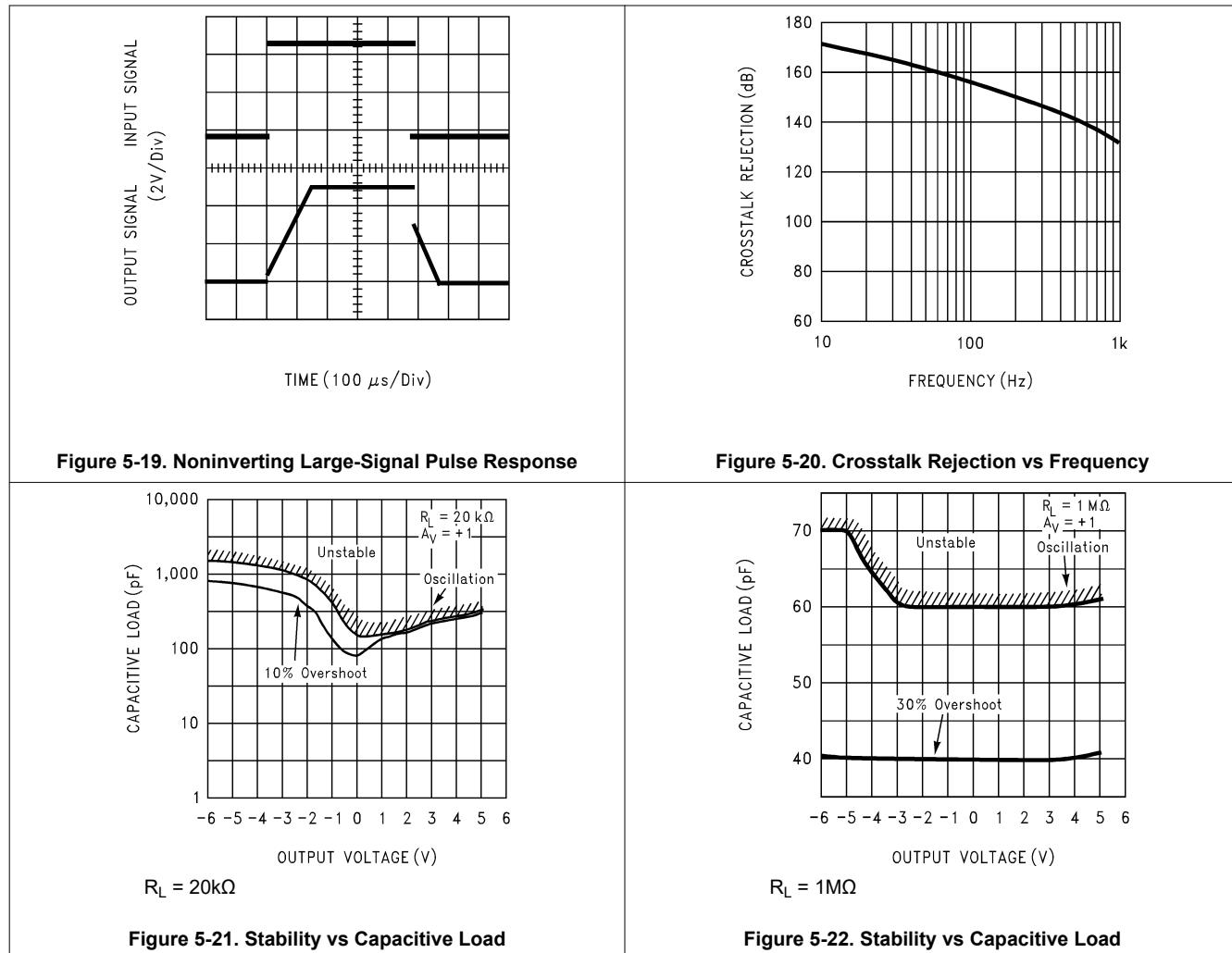


Figure 5-18. Noninverting Small-Signal Pulse Response

5.8 Typical Characteristics (continued)

at $V_S = \pm 7.5V$ and $T_A = 25^\circ C$ (unless otherwise specified)



6 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

6.1 Applications Information

6.1.1 Amplifier Topology

The LMC606x incorporate a novel op amp design topology that enables rail-to-rail output swing even when driving a large load. Special compensation design techniques are incorporated to maintain stability over a wider range of operating conditions than traditional micropower op amps. These features make the LMC606x both easier to design with, and provide higher speed than products typically found in this ultra-low power class.

6.1.2 Compensating For Input Capacitance

Large values of feedback resistance are quite common for amplifiers with ultra-low input current, like the LMC606x. Although the LMC606x is highly stable over a wide range of operating conditions, take certain precautions to achieve the desired pulse response when a large feedback resistor is used. Large feedback resistors and even small values of input capacitance, due to transducers, photodiodes, and circuit board parasitics, reduce phase margins.

When high input impedances are demanded, guarding of the LMC606x is suggested. Guarding input lines can not only reduce leakage, but also lower stray input capacitance. See also [Section 6.3.1.1](#).

The effect of input capacitance can be compensated for by adding a capacitor. Place a capacitor, C_F , around the feedback resistor (as in [Figure 6-1](#)) such that:

$$\frac{1}{2\pi R_1 C_{IN}} \geq \frac{1}{2\pi R_2 C_F} \quad (1)$$

where

$$R_1 C_{IN} \leq R_2 C_F \quad (2)$$

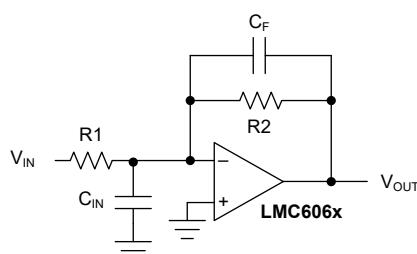


Figure 6-1. Canceling the Effect of Input Capacitance

The exact value of C_{IN} is often difficult to know, but C_F can be experimentally adjusted so that the desired pulse response is achieved. For a more detailed discussion on compensating for input capacitance, see the [LMC660](#) and the [LMC662](#).

6.1.3 Capacitive Load Tolerance

All rail-to-rail output swing operational amplifiers have voltage gain in the output stage. A compensation capacitor is normally included in this integrator stage. The frequency location of the dominate pole is affected by the resistive load on the amplifier. Capacitive load driving capability can be optimized by using an appropriate resistive load in parallel with the capacitive load (see [Section 5.8](#)).

Direct capacitive loading reduces the phase margin of many op amps. A pole in the feedback loop is created by the combination of the output impedance of the op amp and the capacitive load. This pole induces phase lag at the unity-gain crossover frequency of the amplifier resulting in either an oscillatory or underdamped pulse response. [Figure 6-2](#) shows that with a few external components, op amps can easily indirectly drive capacitive loads.

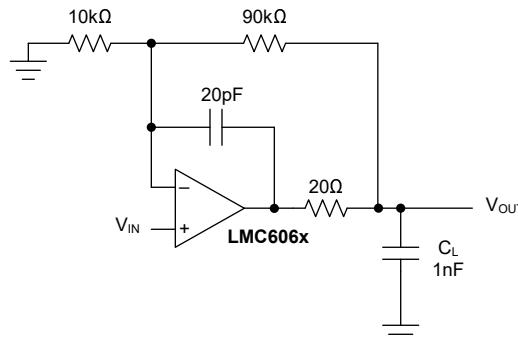


Figure 6-2. LMC606x Noninverting Gain of 10 Amplifier Compensated to Handle Capacitive Loads

In the circuit of [Figure 6-2](#), R1 and C1 serve to counteract the loss of phase margin by feeding the high-frequency component of the output signal back to the inverting input of the amplifier, thereby preserving phase margin in the overall feedback loop.

Capacitive load driving capability is enhanced by using a pullup resistor to V+ ([Figure 6-3](#)). Typically, a pullup resistor conducting 10µA or more can significantly improve capacitive load responses. The value of the pullup resistor must be determined based on the current sinking capability of the amplifier with respect to the desired output swing. The open-loop gain of the amplifier can also be affected by the pullup resistor (see [Section 5.7](#)).

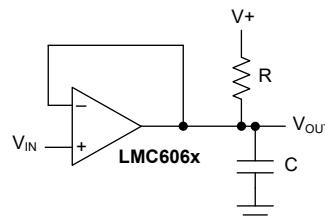


Figure 6-3. Compensating for Large Capacitive Loads With a Pullup Resistor

6.1.4 Latchup

CMOS devices tend to be susceptible to latchup due to internal parasitic silicon controlled rectifier (SCR) effects. The input and output (I/O) pins look similar to the gate of the SCR. There is a minimum current required to trigger the SCR gate lead. The LMC606x are designed to withstand 100mA surge current on the I/O pins. Use a resistive method to isolate any capacitance from supplying excess current to the I/O pins. In addition, like a SCR, there is a minimum holding current for any latchup mode. Limiting current to the supply pins also inhibits latchup susceptibility.

6.2 Typical Applications

6.2.1 Instrumentation Amplifier

The extremely high input impedance, and low power consumption, of the LMC606x make them an excellent choice for applications that require battery-powered instrumentation amplifiers. Examples of these types of applications are portable pH probes, analytic medical instruments, magnetic field detectors, gas detectors, and silicon-based pressure transducers.

Figure 6-4 shows an instrumentation amplifier that features high differential and common mode input resistance ($> 10^{14}\Omega$), 0.01% gain accuracy at $A_V = 100$, excellent CMRR with $1\text{k}\Omega$ imbalance in bridge source resistance. Input current is less than 100fA and offset drift is less than $2.5\mu\text{V}/^\circ\text{C}$. R_2 provides a simple means of adjusting gain over a wide range without degrading CMRR. R_7 is an initial trim used to maximize CMRR without using super precision matched resistors. For good CMRR over temperature, use low-drift resistors.

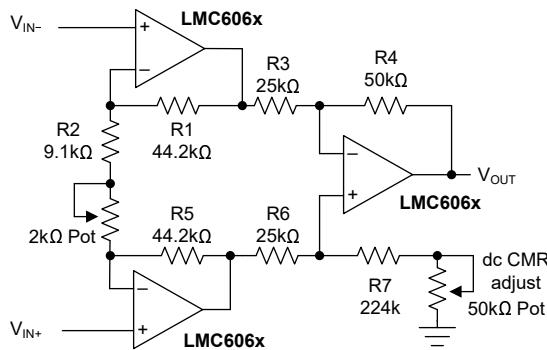


Figure 6-4. Instrumentation Amplifier

If $R_1 = R_5$, $R_3 = R_6$, and $R_4 = R_7$, then

$$\frac{V_{\text{OUT}}}{V_{\text{IN}}} = \frac{R_4}{R_3} \left(\frac{R_2 + 2R_1}{R_2} \right) \quad (3)$$

and $A_V \approx 100$ for the circuit shown in Figure 6-4 ($R_2 = 9.1\text{k}\Omega$). Note that $V_{\text{IN}} = V_{\text{IN}+} - V_{\text{IN}-}$.

6.2.2 Low-Leakage Sample-and-Hold

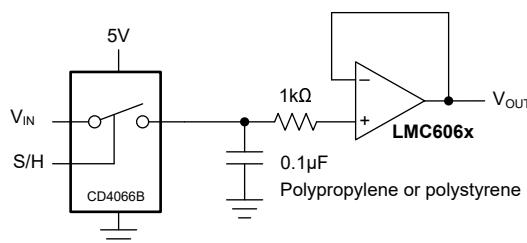


Figure 6-5. Low-Leakage Sample-and-Hold

6.2.3 1Hz Square-Wave Oscillator

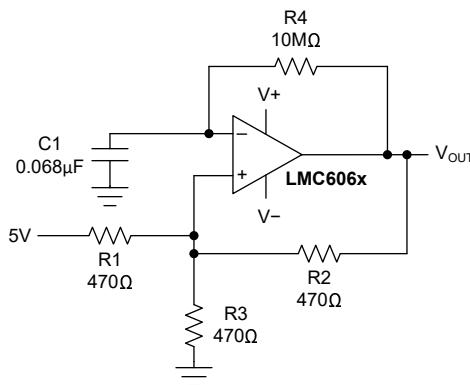


Figure 6-6. 1Hz Square-Wave Oscillator

6.3 Layout

6.3.1 Layout Guidelines

6.3.1.1 Printed Circuit Board Layout For High Impedance Work

Generally, any circuit that must operate with less than 1000pA of leakage current requires special layout of the printed circuit board (PCB). To take advantage of the ultra-low bias current of the LMC606x, typically less than 10fA, having an excellent layout is essential. Fortunately, the techniques used to obtain low leakages are quite simple. First, do not ignore the surface leakage of the PCB, even though the leakage can sometimes appear acceptably low. Under conditions of high humidity, dust, or contamination, the surface leakage can be appreciable.

To minimize the effect of any surface leakage, lay out a ring of foil completely surrounding the LMC606x inputs and the terminals of capacitors, diodes, conductors, resistors, relay terminals, and so on, connected to the op amp inputs, as in [Figure 6-11](#). To have a significant effect, place guard rings on both the top and bottom of the PCB. Then connect this foil to a voltage that is at the same voltage as the amplifier inputs, because no leakage current can flow between two points at the same potential. For example, a PCB trace-to-pad resistance of $10^{12}\Omega$, which is normally considered a very large resistance, can leak 5pA if the trace is a 5V bus adjacent to the pad of the input. This leak can cause a 100 times degradation from the LMC606x actual performance. However, if a guard ring is held within 5mV of the inputs, then even a resistance of $10^{11}\Omega$ causes only 0.05pA of leakage current. See [Figure 6-7](#) to [Figure 6-9](#) for typical connections of guard rings for standard op amp configurations.

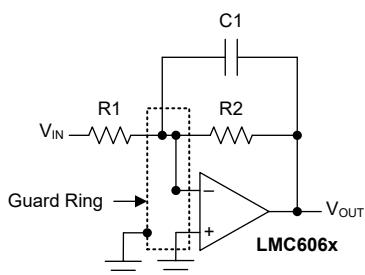


Figure 6-7. Typical Connections of Guard Rings:
Inverting Amplifier

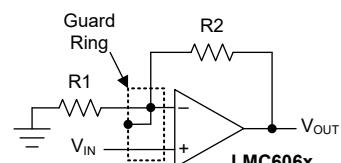


Figure 6-8. Typical Connections of Guard Rings:
Noninverting Amplifier

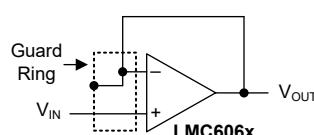
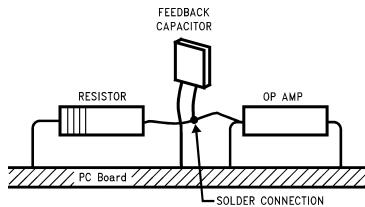


Figure 6-9. Typical Connections of Guard Rings: Follower

When laying out a PCB for the sake of just a few circuits is not practical, the following technique is even better than a guard ring. Do not insert the input pin of the amplifier into the PCB at all. Instead, bend the pin up in the air, and use only air as an insulator. Air is an excellent insulator. In this case, you forgo some of the advantages of PCB construction, but the advantages are sometimes well worth the effort of using point-to-point up-in-the-air wiring. [Figure 6-10](#) shows an example of air wiring.



Note: Input pins are lifted out of the PCB and soldered directly to components. All other pins are connected to the PCB.

Figure 6-10. Air Wiring

6.3.2 Layout Example

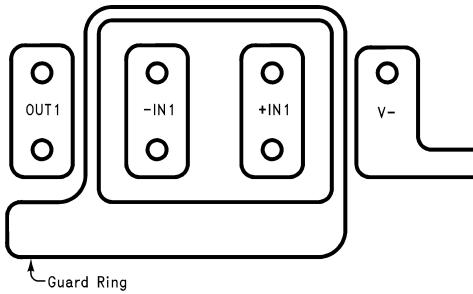


Figure 6-11. Example of Guard Ring in PCB Layout

7 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

7.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

7.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

7.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

7.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

8 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision D (March 2013) to Revision E (March 2025)	Page
• Added LMC6061 and LMC6064 and related content to this data sheet.....	1
• Deleted LMC6061 and LMC6064 PDIP content.....	1
• Added application circuit.....	1
• Added <i>Pin Configuration and Functions</i>	2
• Updated pin names in <i>Pin Configuration and Functions</i>	2
• Added <i>ESD Ratings</i>	5
• Deleted notes 1 and 2 from <i>Recommended Operating Conditions</i>	5
• Added <i>Thermal Information</i>	6
• Updated to combine ac and dc <i>Electrical Characteristics</i>	7
• Updated parameter names and symbols.....	7
• Deleted notes 1, 2, and 3 from dc <i>Electrical Characteristics</i>	7
• Changed input current noise from 0.2fA/√Hz to 12.5fA/Hz.....	7
• Moved note 4 conditions from dc <i>Electrical Characteristics</i> to open-loop voltage gain test conditions.....	7
• Changed open-loop gain for $R_L = 100k\Omega$ (sourcing) from 400V/mV to 300V/mV for LMC606xAI.....	7
• Changed open-loop gain for $R_L = 100k\Omega$ (sourcing, $T_A = -40^\circ C$ to $+85^\circ C$) from 300V/mV to 200V/mV for LMC606xAI.....	7
• Changed open-loop gain for $R_L = 25k\Omega$ (sourcing) from 400V/mV to 300V/mV for LMC606xAI.....	7
• Deleted notes 1, 2, and 3 from ac <i>Electrical Characteristics</i>	7
• Moved note 4 conditions from ac <i>Electrical Characteristics</i> to slew rate test conditions.....	7

• Moved note 5 conditions from ac <i>Electrical Characteristics</i> to crosstalk test conditions.....	7
• Change supply current parameter name to quiescent current per amplifier.....	7
• Updated <i>Amplifier Topology</i>	15

Changes from Revision C (March 2013) to Revision D (March 2013)	Page
• Changed layout of National Data Sheet to TI format.....	17

9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMC6061AIM/NOPB	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 85	LMC60 61AIM
LMC6061AIMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	(6061AI, LMC60) 61AIM
LMC6061AIMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(6061AI, LMC60) 61AIM
LMC6061AIMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(6061AI, LMC60) 61AIM
LMC6061IM/NOPB	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 85	LMC60 61IM
LMC6061IMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 61IM
LMC6061IMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 61IM
LMC6061IMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 61IM
LMC6062AIM/NOPB	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 85	LMC60 62AIM
LMC6062AIMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 62AIM
LMC6062AIMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 62AIM
LMC6062AIMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 62AIM
LMC6062I MDC	Active	Production	DIESALE (Y) 0	288 OTHER	Yes	Call TI	Level-1-NA-UNLIM	-40 to 85	
LMC6062I-MDC.A	Active	Production	DIESALE (Y) 0	288 OTHER	Yes	Call TI	Level-1-NA-UNLIM	-40 to 85	
LMC6062IM/NOPB	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 85	LMC60 62IM
LMC6062IMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 62IM
LMC6062IMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 62IM

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMC6062IMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC6062IM
LMC6062IN/NOPB	Active	Production	PDIP (P) 8	40 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	LMC6062IN
LMC6062IN/NOPB.A	Active	Production	PDIP (P) 8	40 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	LMC6062IN
LMC6062IN/NOPB.B	Active	Production	PDIP (P) 8	40 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	LMC6062IN
LMC6064AIM/NOPB	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-40 to 85	LMC6064AIM
LMC6064AIMX/NOPB	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC6064AIM
LMC6064AIMX/NOPB.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC6064AIM
LMC6064AIMX/NOPB.B	Active	Production	SOIC (D) 14	2500 LARGE T&R	-	Call TI	Call TI	-40 to 85	
LMC6064IM/NOPB	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-40 to 85	LMC6064IM
LMC6064IMX/NOPB	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC6064IM
LMC6064IMX/NOPB.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC6064IM
LMC6064IMX/NOPB.B	Active	Production	SOIC (D) 14	2500 LARGE T&R	-	Call TI	Call TI	-40 to 85	

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

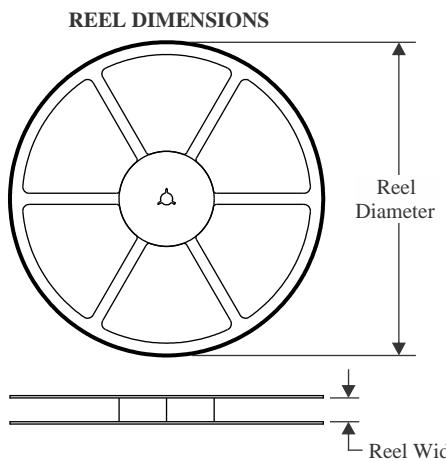
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

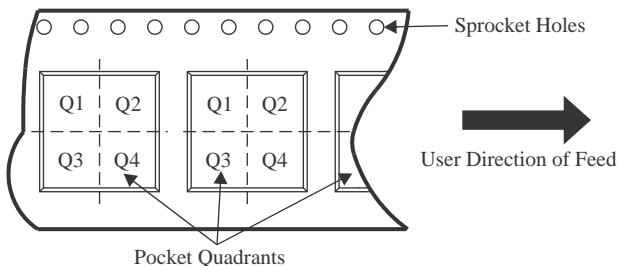
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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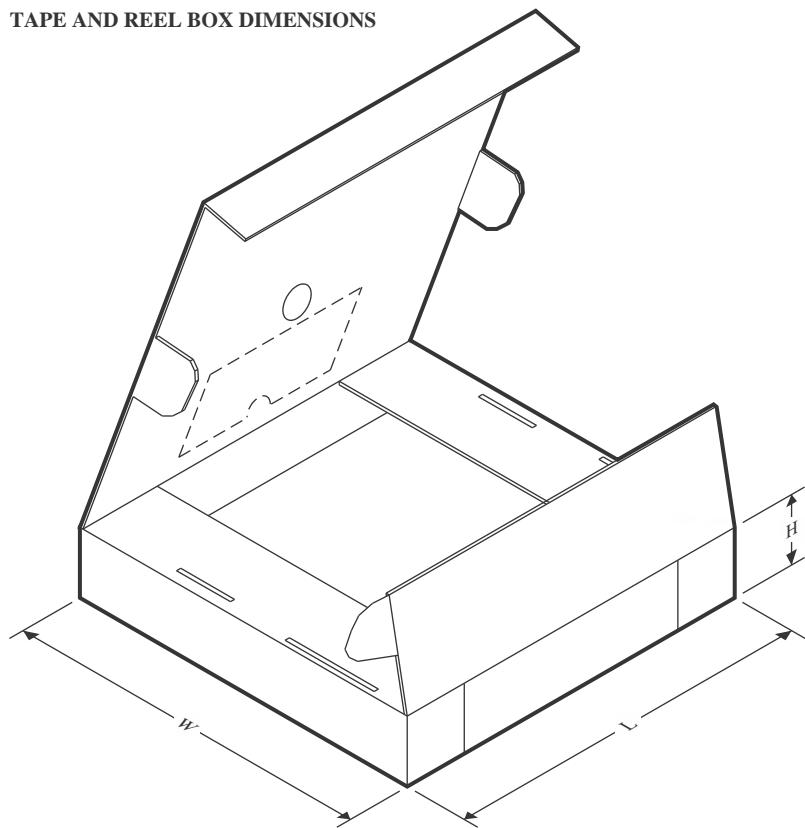
TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


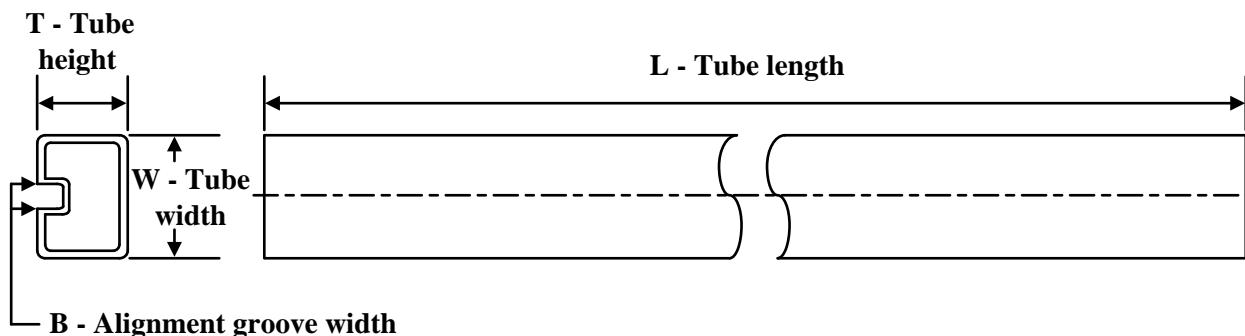
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMC6061AIMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LMC6061IMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LMC6062AIMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LMC6062IMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LMC6064AIMX/NOPB	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1
LMC6064IMX/NOPB	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMC6061AIMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LMC6061IMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LMC6062AIMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LMC6062IMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LMC6064AIMX/NOPB	SOIC	D	14	2500	367.0	367.0	35.0
LMC6064IMX/NOPB	SOIC	D	14	2500	367.0	367.0	35.0

TUBE


*All dimensions are nominal

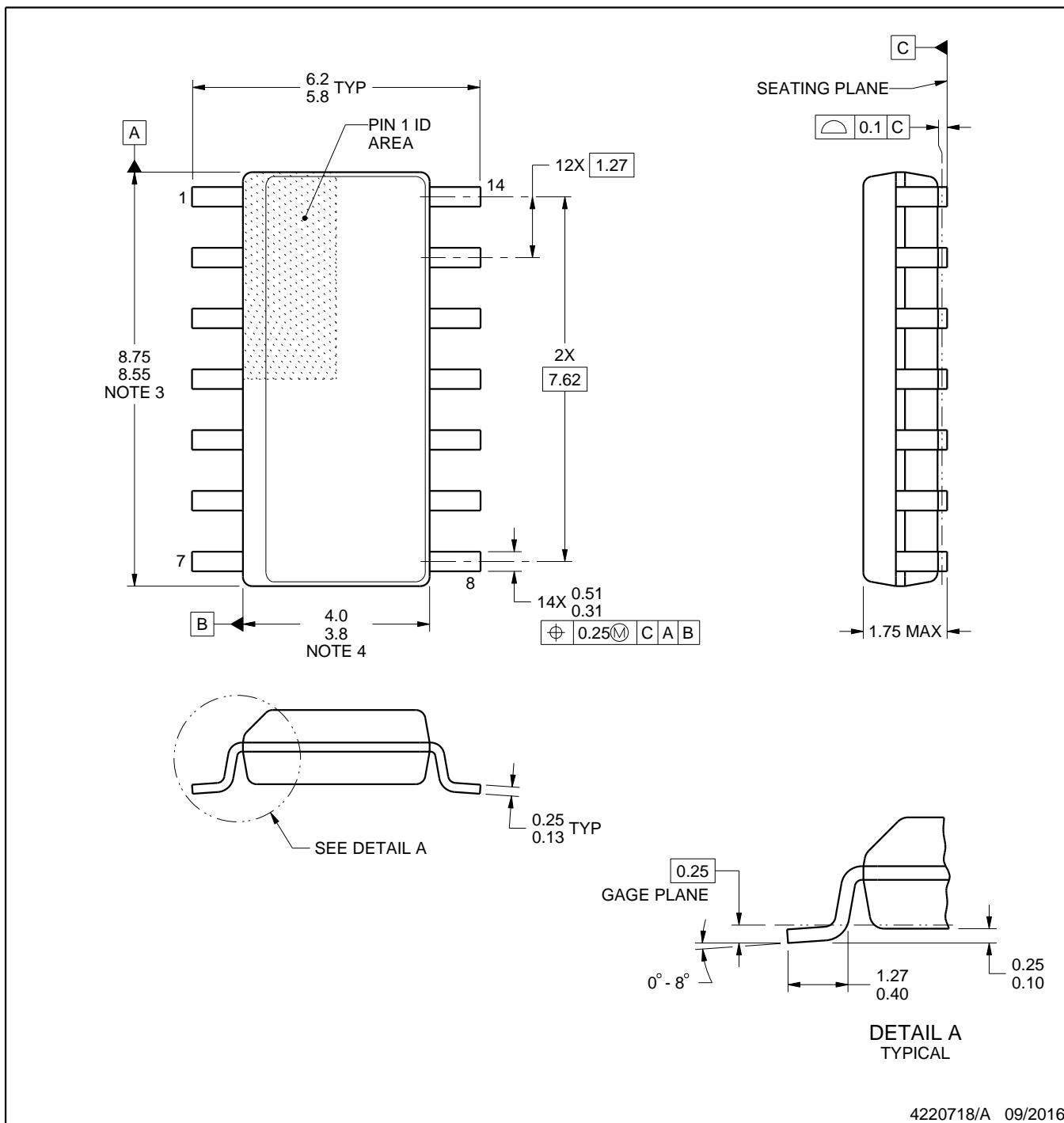
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
LMC6062IN/NOPB	P	PDIP	8	40	502	14	11938	4.32
LMC6062IN/NOPB.A	P	PDIP	8	40	502	14	11938	4.32
LMC6062IN/NOPB.B	P	PDIP	8	40	502	14	11938	4.32

PACKAGE OUTLINE

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

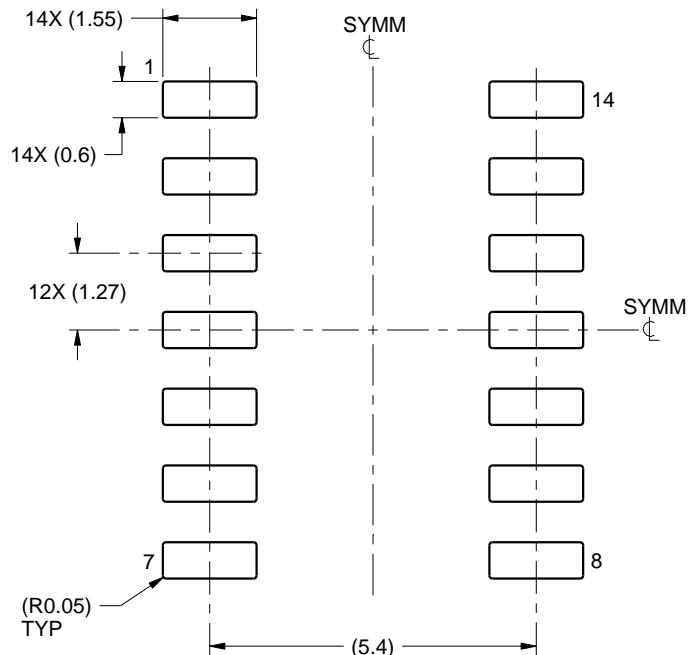
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

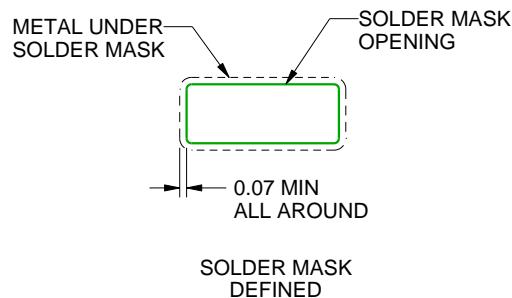
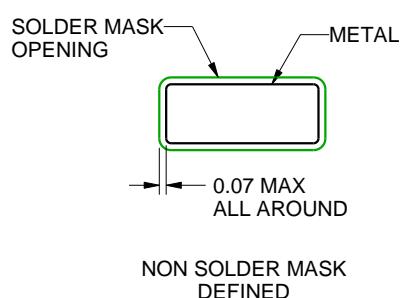
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

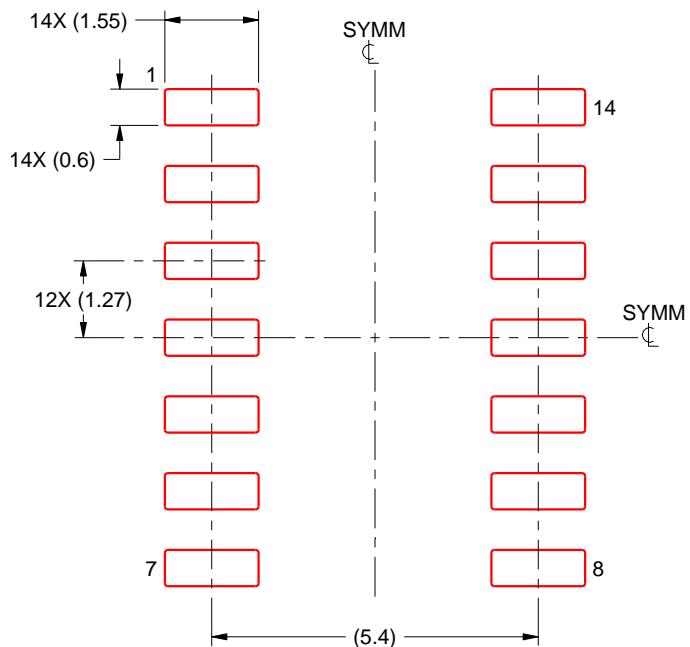
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



**SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X**

4220718/A 09/2016

NOTES: (continued)

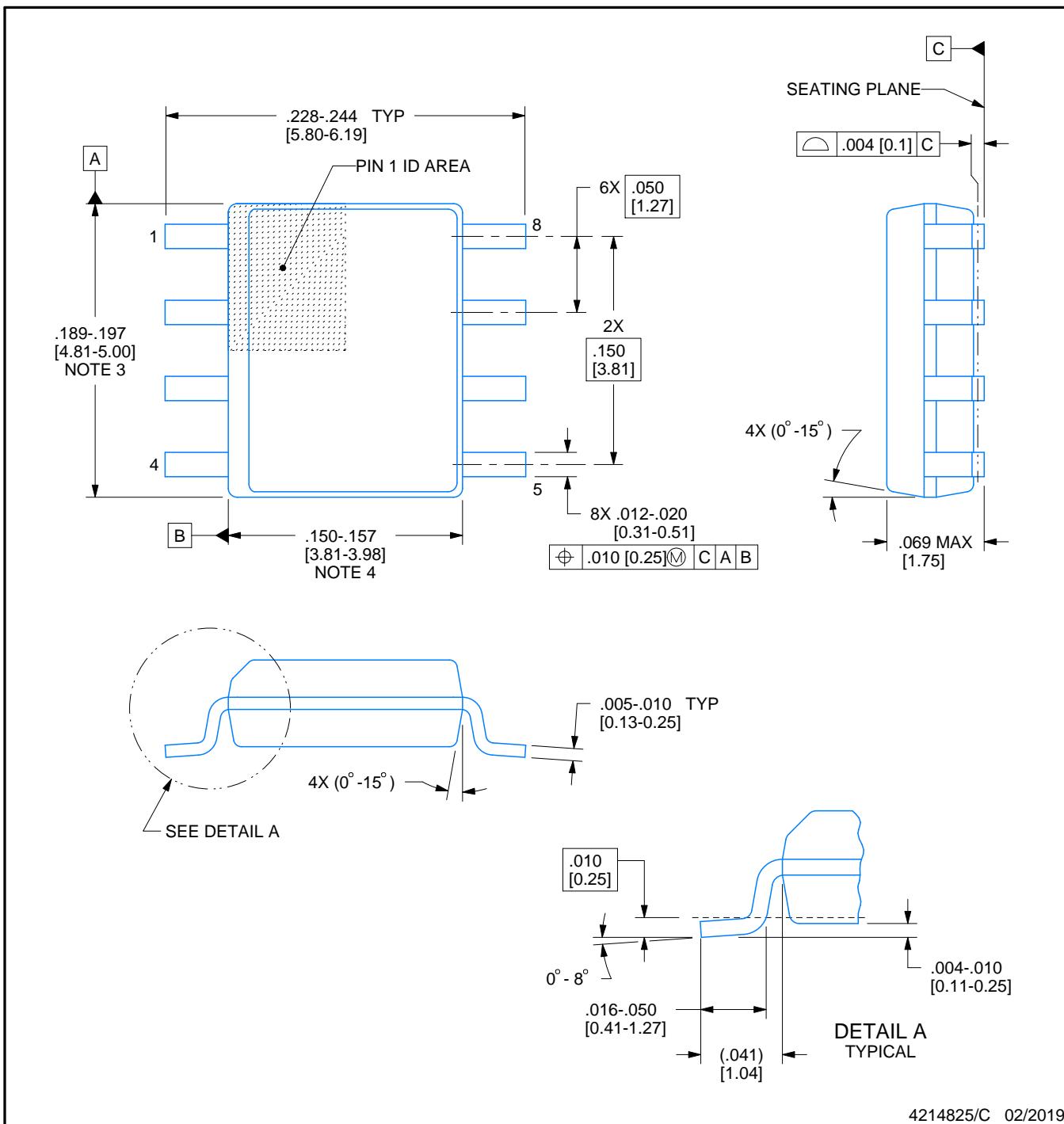
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
 9. Board assembly site may have different recommendations for stencil design.



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

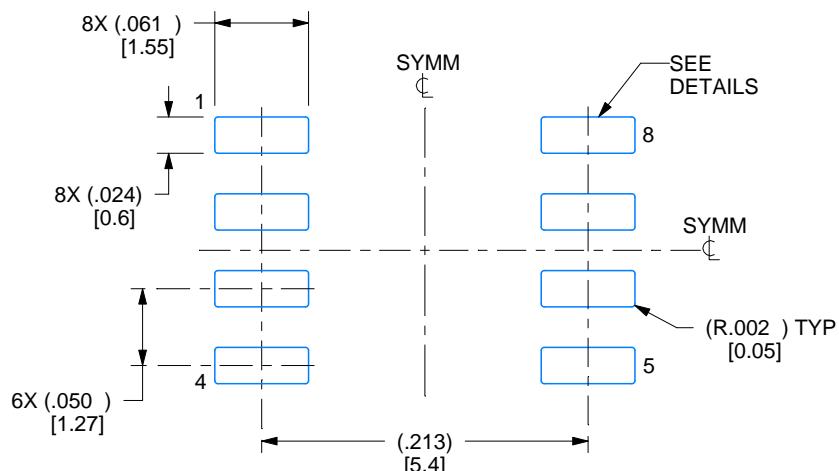
1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

EXAMPLE BOARD LAYOUT

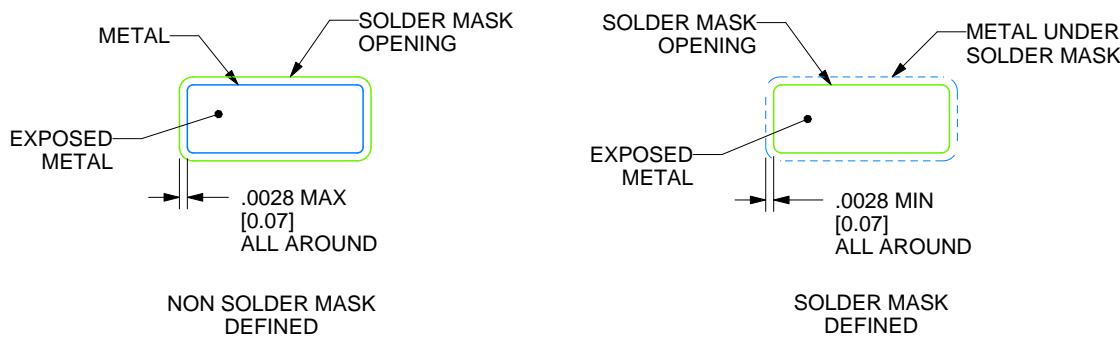
D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

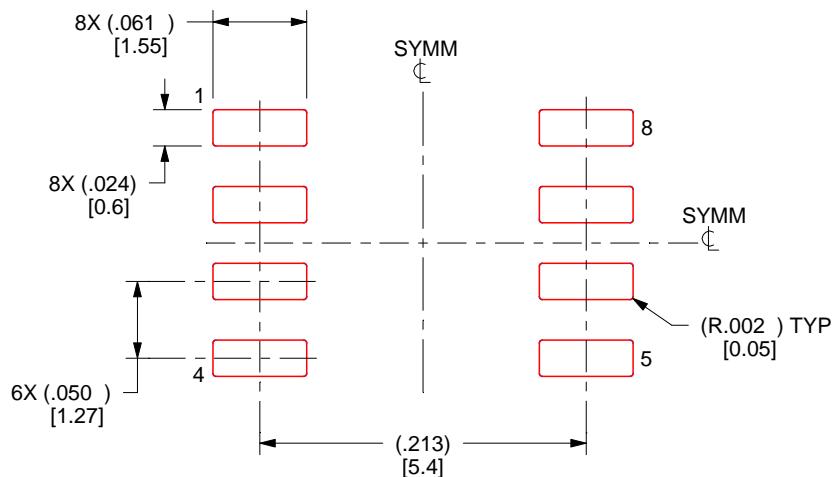
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

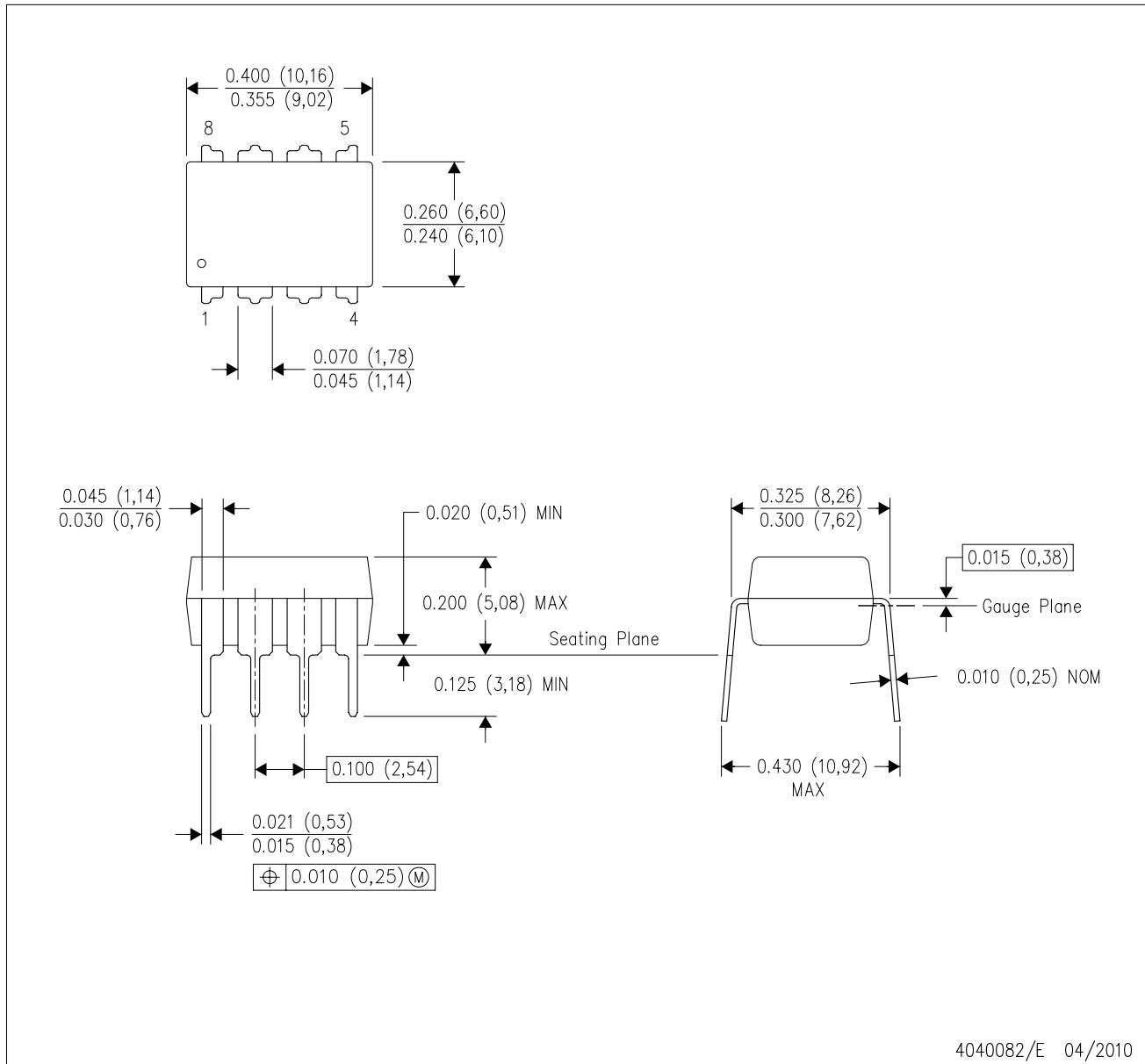
4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001 variation BA.

4040082/E 04/2010

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